MICROFEATURE ASSEMBLIES INCLUDING INTERCONNECT STRUCTURES AND METHODS FOR FORMING SUCH INTERCONNECT STRUCTURES

ABSTRACT OF THE DISCLOSURE

Microfeature assemblies including interconnect structures and methods for forming such interconnect structures are disclosed herein. One particular embodiment of a microfeature assembly includes a microelectronic die having integrated circuitry, a plurality of terminals electrically coupled to the integrated circuitry, and conductive bumps on the individual terminals. The conductive bumps include first engagement features. The assembly also includes a microfeature workpiece having a substrate and a plurality of pads on the substrate. The pads include non-planar second engagement features engaged with the first engagement features on corresponding conductive bumps.

Figure : 2